

**Listing of Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A wiring forming method of supplying a first liquid and a second liquid in such a manner that said first liquid and said second liquid contact with each other on a substrate to thereby form a wiring pattern including the first pattern and the second pattern on the substrate, the method comprising:

a first pattern forming step of supplying the first liquid to thereby form the first pattern on the substrate; and

a second pattern forming step of supplying the second liquid to thereby form the second pattern on the substrate,

wherein a forming order of said first pattern and said second pattern for constituting said wiring pattern in a same layer is changed in accordance with information of said wiring pattern, the information on said wiring pattern including information on where the wiring pattern is to be formed.

2. (Canceled)

3. (Previously Presented) The wiring forming method according to claim 1, wherein curing process is performed each time said first pattern or said second pattern is formed to the substrate.

4. (Canceled)

5. (Original) The wiring forming method according to claim 1, wherein the first pattern forming step comprises the steps of: forming the first patterns on a plurality of positions of the substrate, and thereafter the second pattern forming step comprises the steps of: forming the second pattern between the first patterns formed in the plurality of positions on the substrate in such a manner as to bring the second pattern into contact with the first pattern.
6. (Original) The wiring forming method according to claim 1, further comprising the steps of: discharging the first and second liquids by an ink jet system to thereby supply the liquids onto the substrate.
7. (Canceled)
- 8 (Original) The wiring forming method according to claim 1, wherein the first pattern is an insulated pattern having an insulating property, and the second pattern is a conductive pattern having conductivity.
9. (Original) The wiring forming method according to claim 1, wherein the first and second patterns are insulating insulated patterns having different properties.
10. (Original) The wiring forming method according to claim 1, wherein the first pattern is an insulated pattern having an insulating property, and the second pattern is a semiconductor pattern of a semiconductor.

11. (Withdrawn) A wiring board comprising: a wiring formed by the wiring forming method according to claim 1; and the substrate.

12. (Withdrawn) A wiring forming apparatus for supplying a first liquid forming a first pattern and a second liquid forming a second pattern in such a manner that the first liquid and the second liquid contact with each other on a substrate to there form a wiring pattern including said first pattern and said second wiring pattern on the substrate, the apparatus comprising:

a first liquid container which stores the first liquid;

a second liquid container which stores the second liquid;

first pattern forming means for supplying the first liquid on the substrate from the first liquid container to thereby form the first pattern;

second pattern forming means for supplying the second liquid on the substrate from the second liquid container to thereby form the second pattern; and

means for changing a forming order of said first pattern formed by using said first pattern forming means and said second pattern formed by using said second forming means in accordance with information of said wiring pattern upon forming said wiring pattern in a same layer.

13. – 15. (Canceled)

16. (Withdrawn) The wiring forming apparatus according to claim 12, wherein a size of the corresponding first pattern is changeable in accordance with that of the second pattern to be formed.

17. – 19. (Canceled)